

## Automotive high voltage power Schottky rectifier

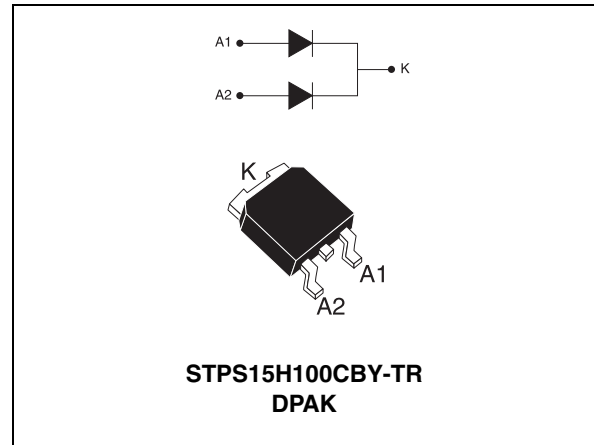
### Features

- Negligible switching losses
- Low leakage current
- Good trade off between leakage current and forward voltage drop
- Low thermal resistance
- Avalanche capability specified
- AEC-Q101 qualified

### Description

Dual center tab Schottky rectifier suited for switched mode power supply and high frequency DC to DC converters.

Packaged in DPAK, this device is intended for use in high frequency inverters in automotive market.



**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	2 x 7.5 A
$V_{RRM}$	100 V
$T_j(max)$	175 °C
$V_{F(max)}$	0.67 V

# 1 Characteristics

**Table 2. Absolute Ratings (limiting values, per diode)**

Symbol	Parameter		Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage		100	V
I <sub>F(RMS)</sub>	Forward rms current		10	A
I <sub>F(AV)</sub>	Average forward current	T <sub>c</sub> = 135 °C Per diode	7.5	A
		δ = 0.5 Per device	15	
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	75	A
I <sub>RRM</sub>	Peak repetitive reverse current	t <sub>p</sub> = 2 μs square F= 1 kHz	1	A
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 1 μs T <sub>j</sub> = 25 °C	6600	W
T <sub>stg</sub>	Storage temperature range		- 65 to + 175	°C
T <sub>j</sub>	Operating junction temperature <sup>(1)</sup> range		-40 to +175	°C
dV/dt	Critical rate of rise of reverse voltage		10000	V/μs

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter		Value	Unit
R <sub>th(j-c)</sub>	Junction to case	Per diode	4	°C/W
		Total	2.4	
R <sub>th(c)</sub>	Coupling		0.7	

When the diodes 1 and 2 are used simultaneously :

$$\Delta T_j(\text{diode } 1) = P(\text{diode } 1) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode } 2) \times R_{th(c)}$$

**Table 4. Static electrical characteristics (per diode)**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>			3	μA
		T <sub>j</sub> = 125 °C			1.3	4	mA
V <sub>F</sub> <sup>(1)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 7.5 A			0.8	V
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 7.5 A		0.62	0.67	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 12 A			0.85	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 12 A		0.68	0.73	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A			0.89	
		T <sub>j</sub> = 125 °C	I <sub>F</sub> = 15 A		0.71	0.76	

1. Pulse test: t<sub>p</sub> = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 0.58 \times I_{F(AV)} + 0.012 I_{F(RMS)}^2$$

Figure 1. Conduction losses versus average current

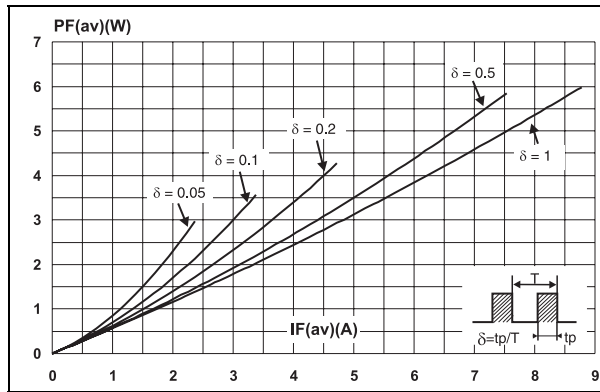


Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )

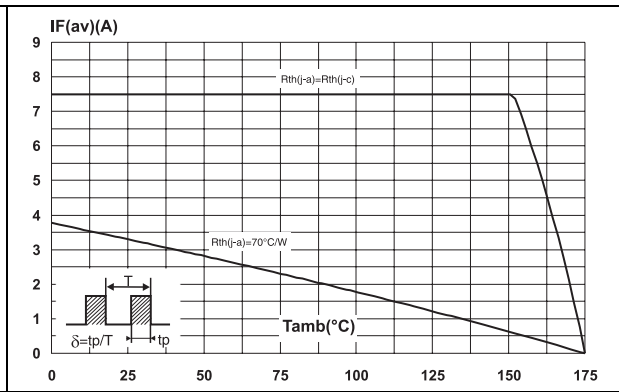


Figure 3. Normalized avalanche power derating versus pulse duration

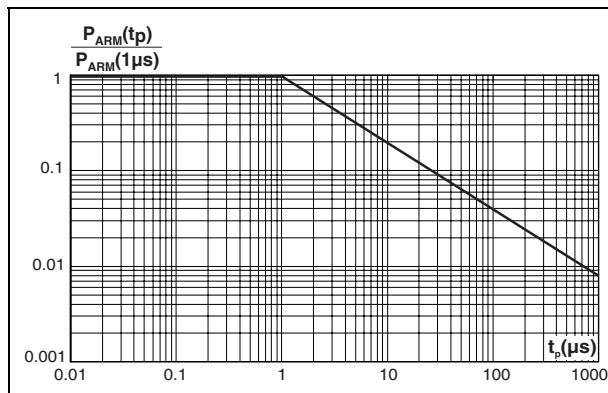


Figure 4. Normalized avalanche power derating versus junction temperature

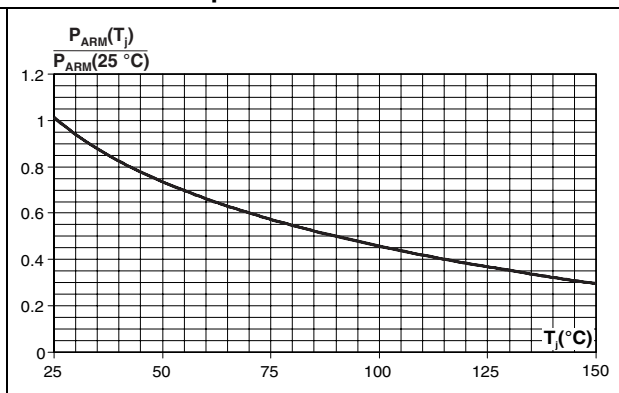


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

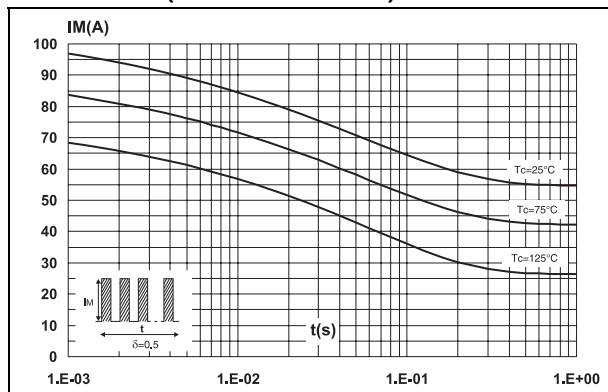
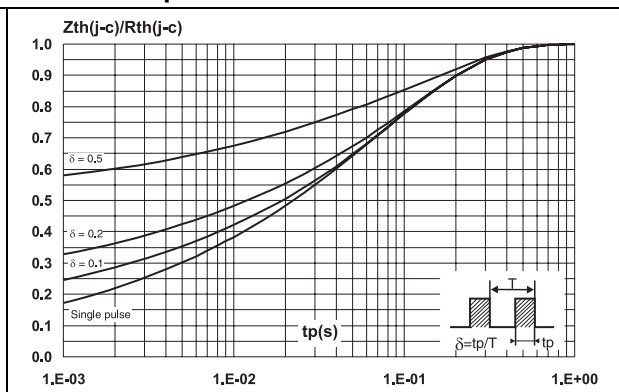
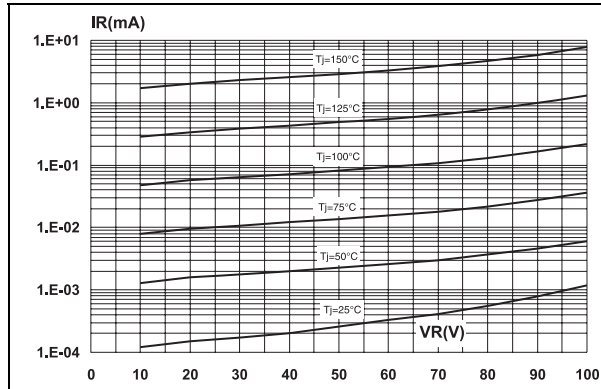


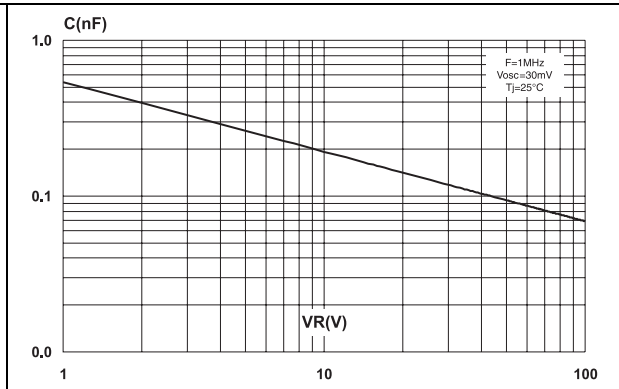
Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



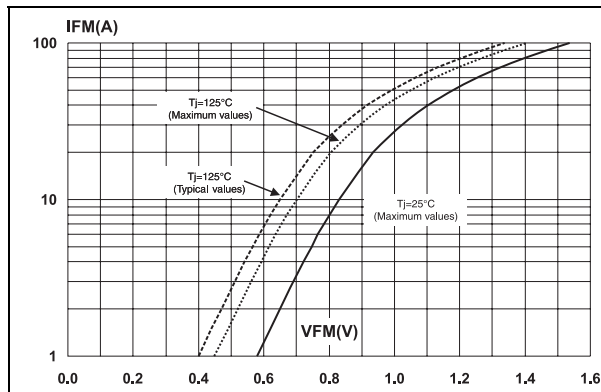
**Figure 7. Reverse leakage current versus reverse voltage applied (typical values)**



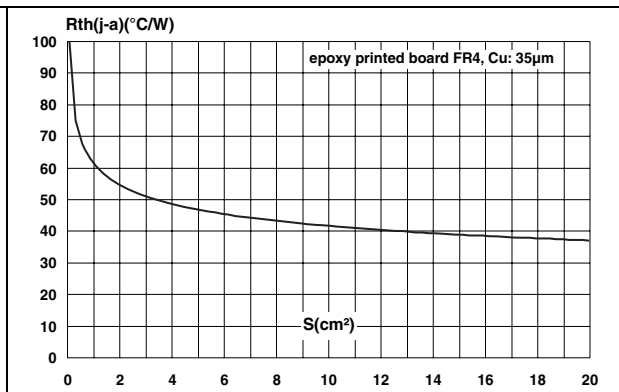
**Figure 8. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 9. Forward voltage drop versus forward current**



**Figure 10. Thermal resistance junction to ambient versus copper surface under tab**



## 2 Package information

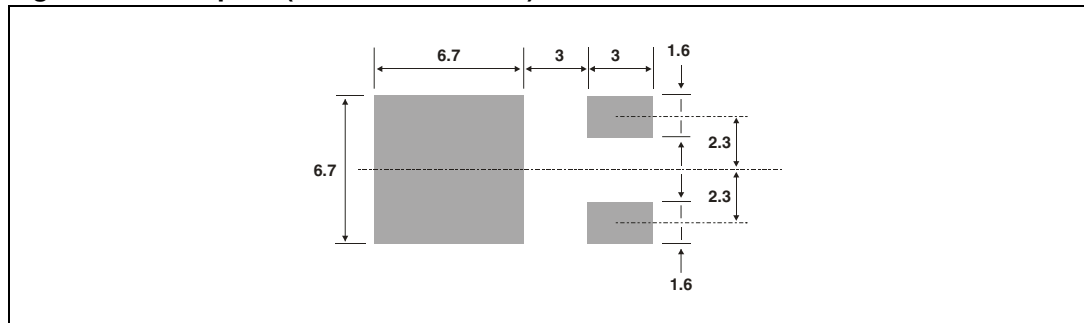
- Epoxy meets UL94,V0
- Lead-free packages

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**Table 5. DPAK dimensions**

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

**Figure 11. Footprint (dimensions in mm)**



### 3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS15H100CBY-TR	S15H100Y	DPAK	0.30 g	75	Tape and reel

### 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
04-Nov-2011	1	Initial release.

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